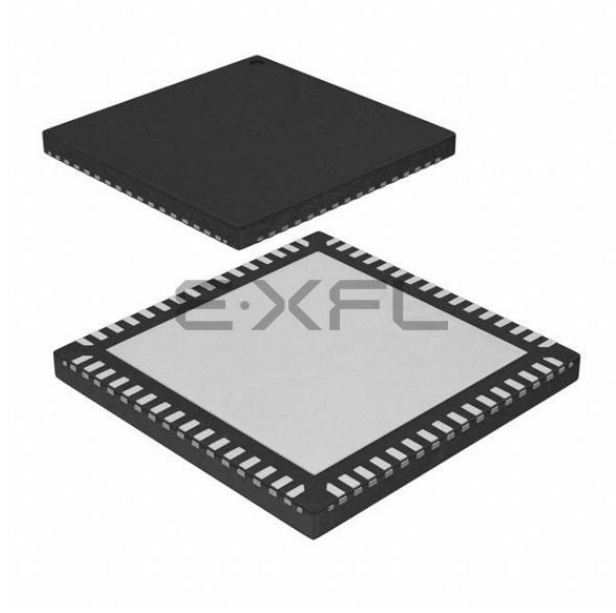
Silicon Labs - EFM32GG11B420F2048GM64-BR Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M4
Core Size	32-Bit Single-Core
Speed	72MHz
Connectivity	CANbus, EBI/EMI, Ethernet, I²C, IrDA, LINbus, MMC/SD/SDIO, QSPI, SmartCard, SPI, UART/USART, USB
Peripherals	Brown-out Detect/Reset, DMA, LCD, POR, PWM, WDT
Number of I/O	53
Program Memory Size	2MB (2M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.8V
Data Converters	A/D 16x12b SAR; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-QFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32gg11b420f2048gm64-br

3.2.4 EM2 and EM3 Power Domains

The EFM32GG11 has three independent peripheral power domains for use in EM2 and EM3. Two of these domains are dynamic and can be shut down to save energy. Peripherals associated with the two dynamic power domains are listed in Table 3.1 EM2 and EM3 Peripheral Power Subdomains on page 13. If all of the peripherals in a peripheral power domain are unused, the power domain for that group will be powered off in EM2 and EM3, reducing the overall current consumption of the device. Other EM2, EM3, and EM4-capable peripherals and functions not listed in the table below reside on the primary power domain, which is always on in EM2 and EM3.

Table 3.1. EM2 and EM3 Peripheral Power Subdomains

Peripheral Power Domain 1	Peripheral Power Domain 2
ACMP0	ACMP1
PCNT0	PCNT1
ADC0	PCNT2
LETIMER0	CSEN
LESENSE	VDAC0
APORT	LEUART0
-	LEUART1
-	LETIMER1
-	I2C0
-	I2C1
-	I2C2
-	IDAC
-	ADC1
-	ACMP2
-	ACMP3
-	LCD
-	RTC

3.3 General Purpose Input/Output (GPIO)

EFM32GG11 has up to 144 General Purpose Input/Output pins. GPIO are organized on three independent supply rails, allowing for interface to multiple logic levels in the system simultaneously. Each GPIO pin can be individually configured as either an output or input. More advanced configurations including open-drain, open-source, and glitch-filtering can be configured for each individual GPIO pin. The GPIO pins can be overridden by peripheral connections, like SPI communication. Each peripheral connection can be routed to several GPIO pins on the device. The input value of a GPIO pin can be routed through the Peripheral Reflex System to other peripherals. The GPIO subsystem supports asynchronous external pin interrupts.

3.4 Clocking

3.4.1 Clock Management Unit (CMU)

The Clock Management Unit controls oscillators and clocks in the EFM32GG11. Individual enabling and disabling of clocks to all peripheral modules is performed by the CMU. The CMU also controls enabling and configuration of the oscillators. A high degree of flexibility allows software to optimize energy consumption in any specific application by minimizing power dissipation in unused peripherals and oscillators.

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit

Note:

1. The minimum voltage required in bypass mode is calculated using R_{BYP} from the DCDC specification table. Requirements for other loads can be calculated as $V_{DVDD\_min}+I_{LOAD} * R_{BYP\_max}$.
2. VREGVDD must be tied to AVDD. Both VREGVDD and AVDD minimum voltages must be satisfied for the part to operate.
3. The system designer should consult the characteristic specs of the capacitor used on DECOUPLE to ensure its capacitance value stays within the specified bounds across temperature and DC bias.
4. VSCALE0 to VSCALE2 voltage change transitions occur at a rate of 10 mV / usec for approximately 20 usec. During this transition, peak currents will be dependent on the value of the DECOUPLE output capacitor, from 35 mA (with a 1 µF capacitor) to 70 mA (with a 2.7 µF capacitor).
5. When the CSEN peripheral is used with chopping enabled (CSEN_CTRL_CHOPEN = ENABLE), IOVDD must be equal to AVDD.
6. The maximum limit on T_A may be lower due to device self-heating, which depends on the power dissipation of the specific application. T_A (max) = T_J (max) - ($THETA_{JA}$ x PowerDissipation). Refer to the Absolute Maximum Ratings table and the Thermal Characteristics table for T_J and $THETA_{JA}$.

4.1.3 Thermal Characteristics

Table 4.3. Thermal Characteristics

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Thermal resistance, QFN64 Package	$THETA_{JA\_QFN64}$	4-Layer PCB, Air velocity = 0 m/s	—	17.8	—	°C/W
		4-Layer PCB, Air velocity = 1 m/s	—	15.4	—	°C/W
		4-Layer PCB, Air velocity = 2 m/s	—	13.8	—	°C/W
Thermal resistance, TQFP64 Package	$THETA_{JA\_TQFP64}$	4-Layer PCB, Air velocity = 0 m/s	—	33.9	—	°C/W
		4-Layer PCB, Air velocity = 1 m/s	—	32.1	—	°C/W
		4-Layer PCB, Air velocity = 2 m/s	—	30.1	—	°C/W
Thermal resistance, TQFP100 Package	$THETA_{JA\_TQFP100}$	4-Layer PCB, Air velocity = 0 m/s	—	44.1	—	°C/W
		4-Layer PCB, Air velocity = 1 m/s	—	37.7	—	°C/W
		4-Layer PCB, Air velocity = 2 m/s	—	35.5	—	°C/W
Thermal resistance, BGA112 Package	$THETA_{JA\_BGA112}$	4-Layer PCB, Air velocity = 0 m/s	—	42.0	—	°C/W
		4-Layer PCB, Air velocity = 1 m/s	—	37.0	—	°C/W
		4-Layer PCB, Air velocity = 2 m/s	—	35.3	—	°C/W
Thermal resistance, BGA120 Package	$THETA_{JA\_BGA120}$	4-Layer PCB, Air velocity = 0 m/s	—	47.9	—	°C/W
		4-Layer PCB, Air velocity = 1 m/s	—	41.8	—	°C/W
		4-Layer PCB, Air velocity = 2 m/s	—	39.6	—	°C/W
Thermal resistance, BGA152 Package	$THETA_{JA\_BGA152}$	4-Layer PCB, Air velocity = 0 m/s	—	35.7	—	°C/W
		4-Layer PCB, Air velocity = 1 m/s	—	31.0	—	°C/W
		4-Layer PCB, Air velocity = 2 m/s	—	29.5	—	°C/W
Thermal resistance, BGA192 Package	$THETA_{JA\_BGA192}$	4-Layer PCB, Air velocity = 0 m/s	—	47.9	—	°C/W
		4-Layer PCB, Air velocity = 1 m/s	—	41.8	—	°C/W
		4-Layer PCB, Air velocity = 2 m/s	—	39.6	—	°C/W

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Current consumption in EM0 mode with all peripherals disabled, DCDC in LP mode[3]	I_{ACTIVE_LPM}	32 MHz HFRCO, CPU running while loop from flash	—	82	—	µA/MHz
		26 MHz HFRCO, CPU running while loop from flash	—	83	—	µA/MHz
		16 MHz HFRCO, CPU running while loop from flash	—	88	—	µA/MHz
		1 MHz HFRCO, CPU running while loop from flash	—	257	—	µA/MHz
Current consumption in EM0 mode with all peripherals disabled and voltage scaling enabled, DCDC in Low Noise CCM mode[1]	$I_{ACTIVE\_CCM\_VS}$	19 MHz HFRCO, CPU running while loop from flash	—	117	—	µA/MHz
		1 MHz HFRCO, CPU running while loop from flash	—	1231	—	µA/MHz
Current consumption in EM0 mode with all peripherals disabled and voltage scaling enabled, DCDC in LP mode[3]	$I_{ACTIVE\_LPM\_VS}$	19 MHz HFRCO, CPU running while loop from flash	—	72	—	µA/MHz
		1 MHz HFRCO, CPU running while loop from flash	—	219	—	µA/MHz
Current consumption in EM1 mode with all peripherals disabled, DCDC in Low Noise DCM mode[2]	I_{EM1_DCM}	72 MHz HFRCO	—	42	—	µA/MHz
		50 MHz crystal	—	46	—	µA/MHz
		48 MHz HFRCO	—	46	—	µA/MHz
		32 MHz HFRCO	—	53	—	µA/MHz
		26 MHz HFRCO	—	57	—	µA/MHz
		16 MHz HFRCO	—	72	—	µA/MHz
		1 MHz HFRCO	—	663	—	µA/MHz
Current consumption in EM1 mode with all peripherals disabled, DCDC in Low Power mode[3]	I_{EM1_LPM}	32 MHz HFRCO	—	42	—	µA/MHz
		26 MHz HFRCO	—	43	—	µA/MHz
		16 MHz HFRCO	—	48	—	µA/MHz
		1 MHz HFRCO	—	219	—	µA/MHz
Current consumption in EM1 mode with all peripherals disabled and voltage scaling enabled, DCDC in Low Noise DCM mode[2]	$I_{EM1\_DCM\_VS}$	19 MHz HFRCO	—	60	—	µA/MHz
		1 MHz HFRCO	—	637	—	µA/MHz
Current consumption in EM1 mode with all peripherals disabled and voltage scaling enabled. DCDC in LP mode[3]	$I_{EM1\_LPM\_VS}$	19 MHz HFRCO	—	39	—	µA/MHz
		1 MHz HFRCO	—	190	—	µA/MHz
Current consumption in EM2 mode, with voltage scaling enabled, DCDC in LP mode[3]	I_{EM2_VS}	Full 512 kB RAM retention and RTCC running from LFXO	—	2.8	—	µA
		Full 512 kB RAM retention and RTCC running from LFRCO	—	3.1	—	µA
		16 kB (1 bank) RAM retention and RTCC running from LFRCO[5]	—	2.1	—	µA
Current consumption in EM3 mode, with voltage scaling enabled	I_{EM3_VS}	Full 512 kB RAM retention and CRYOTIMER running from ULFRCO	—	2.4	—	µA

4.1.11 Flash Memory Characteristics[5]

Table 4.19. Flash Memory Characteristics[5]

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Flash erase cycles before failure	EC_{FLASH}		10000	—	—	cycles
Flash data retention	RET_{FLASH}	T ≤ 85 °C	10	—	—	years
		T ≤ 125 °C	10	—	—	years
Word (32-bit) programming time	t_{W_PROG}	Burst write, 128 words, average time per word	20	26.2	32	µs
		Single word	59	68.7	83	µs
Page erase time[4]	t_{PERASE}		20	26.8	35	ms
Mass erase time[1]	t_{MERASE}		20	26.9	35	ms
Device erase time[2 3]	t_{DERASE}	T ≤ 85 °C	—	80.7	95	ms
		T ≤ 125 °C	—	80.7	100	ms
Erase current[6]	I_{ERASE}	Page Erase	—	—	1.7	mA
		Mass or Device Erase	—	—	2.1	mA
Write current[6]	I_{WRITE}		—	—	3.9	mA
Supply voltage during flash erase and write	V_{FLASH}		1.62	—	3.6	V

Note:

1. Mass erase is issued by the CPU and erases all flash.
2. Device erase is issued over the AAP interface and erases all flash, SRAM, the Lock Bit (LB) page, and the User data page Lock Word (ULW).
3. From setting the DEVICEERASE bit in AAP_CMD to 1 until the ERASEBUSY bit in AAP_STATUS is cleared to 0. Internal setup and hold times for flash control signals are included.
4. From setting the ERASEPAGE bit in MSC_WRITECMD to 1 until the BUSY bit in MSC_STATUS is cleared to 0. Internal setup and hold times for flash control signals are included.
5. Flash data retention information is published in the Quarterly Quality and Reliability Report.
6. Measured at 25 °C.

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
ADC clock frequency	f_{ADCCLK}		—	—	16	MHz
Throughput rate	$f_{ADCRATE}$		—	—	1	Msps
Conversion time[1]	$t_{ADCCONV}$	6 bit	—	7	—	cycles
		8 bit	—	9	—	cycles
		12 bit	—	13	—	cycles
Startup time of reference generator and ADC core	$t_{ADCSTART}$	WARMUPMODE[4] = NORMAL	—	—	5	µs
		WARMUPMODE[4] = KEEPIN-STANDBY	—	—	2	µs
		WARMUPMODE[4] = KEEPINSLO-WACC	—	—	1	µs
SNDR at 1Msps and f_{IN} = 10kHz	$SNDR_{ADC}$	Internal reference[7], differential measurement	TBD	67	—	dB
		External reference[6], differential measurement	—	68	—	dB
Spurious-free dynamic range (SFDR)	$SFDR_{ADC}$	1 MSamples/s, 10 kHz full-scale sine wave	—	75	—	dB
Differential non-linearity (DNL)	DNL_{ADC}	12 bit resolution, No missing co-des	TBD	—	TBD	LSB
Integral non-linearity (INL), End point method	INL_{ADC}	12 bit resolution	TBD	—	TBD	LSB
Offset error	$V_{ADCOFFSETERR}$		TBD	0	TBD	LSB
Gain error in ADC	$V_{ADCGAIN}$	Using internal reference	—	-0.2	TBD	%
		Using external reference	—	-1	—	%
Temperature sensor slope	V_{TS_SLOPE}		—	-1.84	—	mV/°C

Note:

1. Derived from ADCCLK.
2. PSRR is referenced to AVDD when ANASW=0 and to DVDD when ANASW=1 in EMU_PWRCTRL.
3. In ADCn_BIASPROG register.
4. In ADCn_CNTL register.
5. The absolute voltage allowed at any ADC input is dictated by the power rail supplied to on-chip circuitry, and may be lower than the effective full scale voltage. All ADC inputs are limited to the ADC supply (AVDD or DVDD depending on EMU_PWRCTRL_ANASW). Any ADC input routed through the APORT will further be limited by the IOVDD supply to the pin.
6. External reference is 1.25 V applied externally to ADCnEXTREFP, with the selection CONF in the SINGLECTRL_REF or SCANCTRL_REF register field and VREFP in the SINGLECTRLX_VREFSEL or SCANCTRLX_VREFSEL field. The differential input range with this configuration is ± 1.25 V.
7. Internal reference option used corresponds to selection 2V5 in the SINGLECTRL_REF or SCANCTRL_REF register field. The differential input range with this configuration is ± 1.25 V. Typical value is characterized using full-scale sine wave input. Minimum value is production-tested using sine wave input at 1.5 dB lower than full scale.

4.1.15 Analog Comparator (ACMP)

Table 4.23. Analog Comparator (ACMP)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Input voltage range	V_{ACMPIN}	ACMPVDD = ACMPn_CTRL_PWRSEL [1]	—	—	$V_{ACMPVDD}$	V
Supply voltage	$V_{ACMPVDD}$	BIASPROG[4] ≤ 0x10 or FULLBIAS[4] = 0	1.8	—	$V_{VREGVDD\_MAX}$	V
		0x10 < BIASPROG[4] ≤ 0x20 and FULLBIAS[4] = 1	2.1	—	$V_{VREGVDD\_MAX}$	V
Active current not including voltage reference[2]	I_{ACMP}	BIASPROG[4] = 1, FULLBIAS[4] = 0	—	50	—	nA
		BIASPROG[4] = 0x10, FULLBIAS[4] = 0	—	306	—	nA
		BIASPROG[4] = 0x02, FULLBIAS[4] = 1	—	6.5	—	µA
		BIASPROG[4] = 0x20, FULLBIAS[4] = 1	—	74	TBD	µA
Current consumption of internal voltage reference[2]	$I_{ACMPREF}$	VLP selected as input using 2.5 V Reference / 4 (0.625 V)	—	50	—	nA
		VLP selected as input using VDD	—	20	—	nA
		VBDIV selected as input using 1.25 V reference / 1	—	4.1	—	µA
		VADIV selected as input using VDD/1	—	2.4	—	µA

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit

Note:

1. ACMPVDD is a supply chosen by the setting in ACMPn_CTRL_PWRSEL and may be IOVDD, AVDD or DVDD.
2. The total ACMP current is the sum of the contributions from the ACMP and its internal voltage reference. $I_{ACMPTOTAL} = I_{ACMP} + I_{ACMPREF}$.
3. ± 100 mV differential drive.
4. In ACMPn_CTRL register.
5. In ACMPn_HYSTERESIS registers.
6. In ACMPn_INPUTSEL register.

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Supply current, continuous conversions, WARMUP-MODE=KEEPCSENWARM	I_{CSEN_ACTIVE}	SAR or Delta Modulation conversions of 33 pF capacitor, CS0CG=0 (Gain = 10x), always on	—	90.5	—	µA
HFPERCLK supply current	$I_{CSEN\_HFPERCLK}$	Current contribution from HFPERCLK when clock to CSEN block is enabled.	—	2.25	—	µA/MHz

Note:

1. Current is specified with a total external capacitance of 33 pF per channel. Average current is dependent on how long the module is actively sampling channels within the scan period, and scales with the number of samples acquired. Supply current for a specific application can be estimated by multiplying the current per sample by the total number of samples per period (total_current = single_sample_current * (number_of_channels * accumulation)).

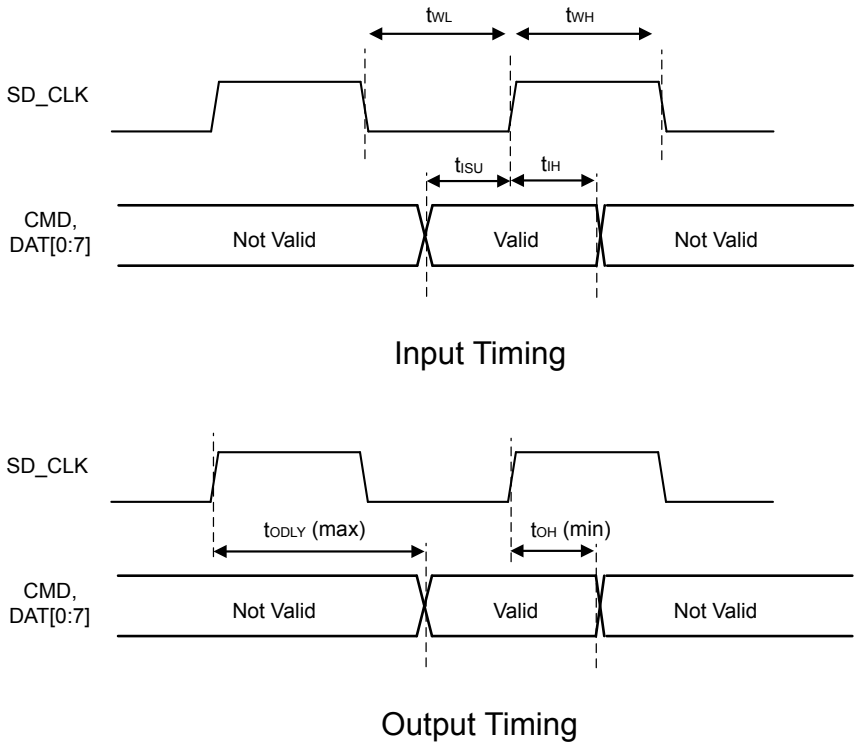

Figure 4.18. SDIO MMC SDR Mode Timing

5.12 EFM32GG11B8xx in QFP64 Device Pinout

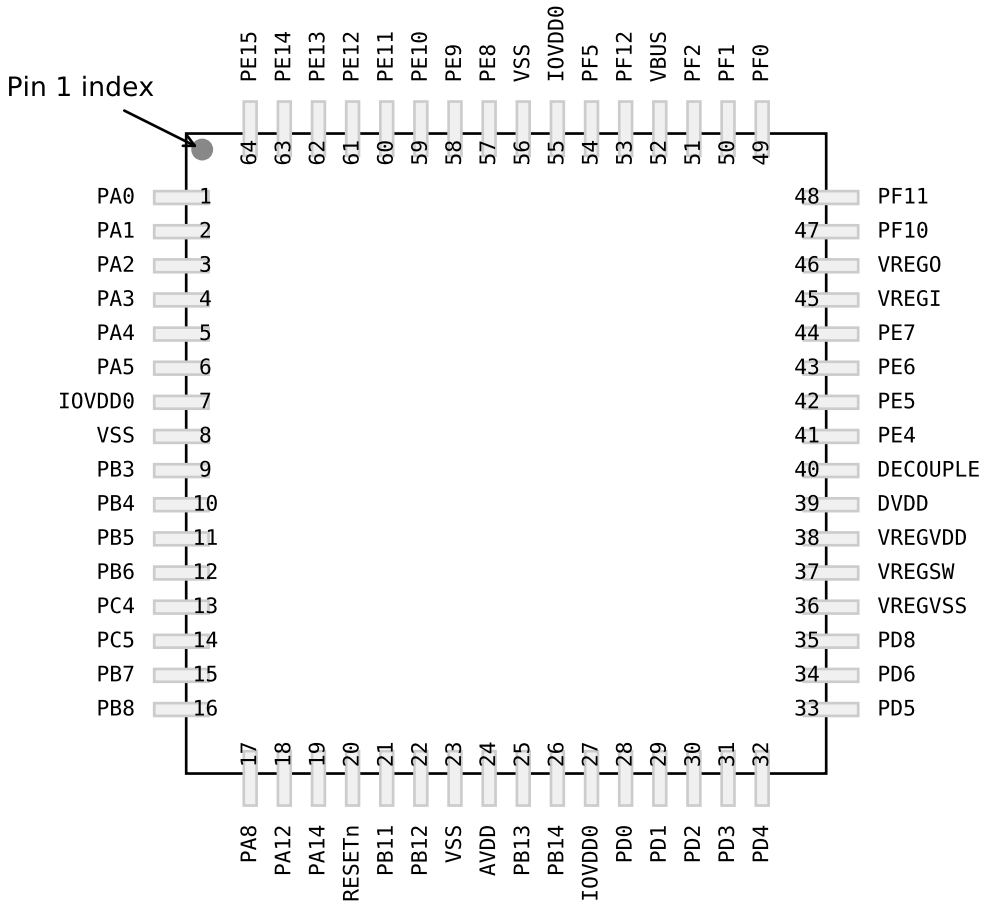

Figure 5.12. EFM32GG11B8xx in QFP64 Device Pinout

The following table provides package pin connections and general descriptions of pin functionality. For detailed information on the supported features for each GPIO pin, see 5.20 GPIO Functionality Table or 5.21 Alternate Functionality Overview.

Table 5.12. EFM32GG11B8xx in QFP64 Device Pinout

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PA0	1	GPIO	PA1	2	GPIO
PA2	3	GPIO	PA3	4	GPIO
PA4	5	GPIO	PA5	6	GPIO
IOVDD0	7 27 55	Digital IO power supply 0.	VSS	8 23 56	Ground
PB3	9	GPIO	PB4	10	GPIO
PB5	11	GPIO	PB6	12	GPIO

5.14 EFM32GG11B4xx in QFP64 Device Pinout

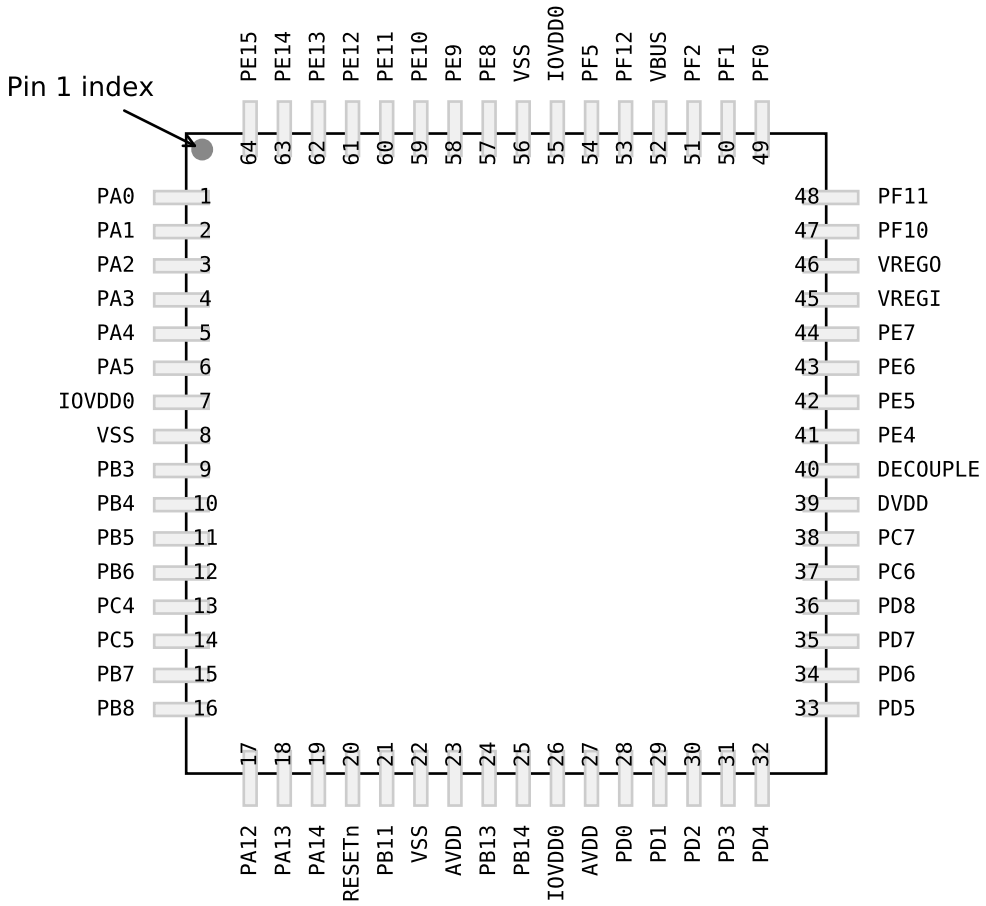

Figure 5.14. EFM32GG11B4xx in QFP64 Device Pinout

The following table provides package pin connections and general descriptions of pin functionality. For detailed information on the supported features for each GPIO pin, see 5.20 GPIO Functionality Table or 5.21 Alternate Functionality Overview.

Table 5.14. EFM32GG11B4xx in QFP64 Device Pinout

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PA0	1	GPIO	PA1	2	GPIO
PA2	3	GPIO	PA3	4	GPIO
PA4	5	GPIO	PA5	6	GPIO
IOVDD0	7 26 55	Digital IO power supply 0.	VSS	8 22 56	Ground
PB3	9	GPIO	PB4	10	GPIO
PB5	11	GPIO	PB6	12	GPIO

GPIO Name	Pin Alternate Functionality / Description				
	Analog	EBI	Timers	Communication	Other
PE6	BUSDY BUSCX LCD_COM2	EBI_A13 #0 EBI_A18 #1 EBI_A24 #3	TIM3_CC1 #3 TIM5_CC2 #0 TIM6_CDTI2 #2 WTIM0_CC2 #0 WTIM1_CC3 #4	US0_RX #1 US3_TX #1	PRS_CH6 #2
PE7	BUSCY BUSDX LCD_COM3	EBI_A14 #0 EBI_A19 #1 EBI_A25 #3	TIM3_CC2 #3 TIM5_CC0 #1 WTIM1_CC0 #5	US0_TX #1 US3_RX #1	PRS_CH7 #2
PG11		EBI_AD11 #2	TIM6_CDTI2 #1 WTIM0_CDTI0 #3	ETH_MIIRXD0 #1 CAN1_TX #6 US3_RTS #5 QSPI0_DQS #2	ETM_TD3 #5
PG10		EBI_AD10 #2	TIM2_CC2 #6 TIM6_CDTI1 #1 WTIM0_CC2 #3	ETH_MIIRXD1 #1 CAN1_RX #6 US3_CTS #3 QSPI0_CS1 #2	
PG9		EBI_AD09 #2	TIM2_CC1 #6 TIM6_CDTI0 #1 WTIM0_CC1 #3	ETH_MIIRXD2 #1 CAN0_TX #4 US3_CTS #5 QSPI0_CS0 #2	
PE3	BU_STAT	EBI_A10 #0 EBI_A15 #1	TIM3_CC0 #2 WTIM1_CC0 #4	US0_CTS #1 U0_RTS #1 U1_RX #3	ACMP1_O #1
PE4	BUSDY BUSCX LCD_COM0	EBI_A11 #0 EBI_A16 #1 EBI_A22 #3	TIM3_CC1 #2 TIM5_CC0 #0 TIM6_CDTI0 #2 WTIM0_CC0 #0 WTIM1_CC1 #4	US0_CS #1 US1_CS #5 US3_CS #1 U0_RX #6 U1_CTS #3 I2C0_SDA #7	PRS_CH16 #2
PG14		EBI_AD14 #2	TIM6_CC2 #2 WTIM2_CC0 #4 PCNT1_S0IN #7	ETH_MIICRS #1 US0_CLK #6	ETM_TD0 #5
PG13		EBI_AD13 #2	TIM6_CC1 #2 WTIM0_CDTI2 #3 WTIM2_CC2 #3	ETH_MIIRXER #1 US0_RX #6	ETM_TD1 #5
PG12		EBI_AD12 #2	TIM6_CC0 #2 WTIM0_CDTI1 #3 WTIM2_CC1 #3	ETH_MIIRXDV #1 US0_TX #6	ETM_TD2 #5
PE1	BUSCY BUSDX	EBI_A01 #2 EBI_A08 #0	TIM3_CC1 #1 WTIM1_CC2 #3 PCNT0_S1IN #1	CAN0_TX #6 U0_RX #1 I2C1_SCL #2	CMU_CLKI0 #4 PRS_CH23 #1 ACMP2_O #2
PE2	BU_VOUT	EBI_A09 #0 EBI_A14 #1	TIM3_CC2 #1 WTIM1_CC3 #3	US0_RTS #1 U0_CTS #1 U1_TX #3	PRS_CH20 #2 ACMP0_O #1
PG15		EBI_AD15 #2	WTIM2_CC1 #4 PCNT1_S1IN #7	ETH_MIICOL #1 US0_CS #6	ETM_TCLK #5
PB15	BUSAY BUSBX	EBI_CS3 #1 EBI_ARDY #2	TIM3_CC1 #7	ETH_TSUTMRTOG #1 SDIO_WP #2 US2_RTS #1 US5_RTS #1	PRS_CH17 #1 ETM_TD2 #1

GPIO Name	Pin Alternate Functionality / Description				
	Analog	EBI	Timers	Communication	Other
PH14	BUSACMP3Y BUSACMP3X	EBI_A26 #2	TIM5_CC1 #2 WTIM1_CC2 #7 PCNT2_S0IN #7	US5_CTS #3 U1_RTS #5 I2C1_SCL #6	
PH15	BUSACMP3Y BUSACMP3X	EBI_A27 #2	TIM5_CC2 #2 WTIM1_CC3 #7 PCNT2_S1IN #6	US5_RTS #3	
PD2	BUSADC0Y BUSADC0X	EBI_A06 #1 EBI_A15 #3 EBI_A27 #0	TIM0_CC1 #2 TIM6_CC1 #6 WTIM1_CC0 #1	US1_CLK #1 LEU1_TX #2	DBG_SWO #3
PD7	BUSADC0Y BUSADC0X ADC0_EXTN ADC1_EXTN OPA1_N	EBI_A11 #1 EBI_A20 #3	TIM1_CC1 #4 WTIM1_CC1 #2 LETIM0_OUT1 #0 PCNT0_S1IN #3	US1_TX #2 US3_CLK #1 U0_TX #6 I2C0_SCL #1	CMU_CLK0 #2 LES_ALTEX1 ACMP1_O #2 ETM_TCLK #0
PB8	LFXTAL_N		TIM0_CDTI1 #4 TIM1_CC1 #3	US0_RX #4 US1_CS #0 US4_RX #0 U0_RTS #4	CMU_CLKI0 #2 PRS_CH23 #0
PC4	BUSACMP0Y BUSACMP0X OPA0_P	EBI_AD11 #1 EBI_ALE #2 EBI_NANDREn #3 EBI_A26 #0	TIM0_CC0 #5 TIM0_CDTI2 #3 TIM2_CC2 #5 LETIM0_OUT0 #3 PCNT1_S0IN #3	SDIO_CD #1 US2_CLK #0 US4_CLK #0 U0_TX #4 U1_CTS #4 I2C1_SDA #0	LES_CH4 PRS_CH18 #2 GPIO_EM4WU6
PA7	BUSAY BUSBX LCD_SEG35	EBI_AD13 #1 EBI_A01 #3 EBI_CSTFT #0	TIM0_CC2 #5 LETIM1_OUT0 #0 PCNT1_S0IN #4	US2_TX #2 US4_CTS #0 US5_RX #1	PRS_CH7 #1
PA10	BUSBY BUSAX LCD_SEG38	EBI_CS0 #1 EBI_A04 #3 EBI_VSNC #0	TIM2_CC2 #0 TIM0_CC2 #6 WTIM2_CC1 #0	US2_CS #2	PRS_CH10 #0
PA12	BUSBY BUSAX	EBI_CS2 #1 EBI_REn #2 EBI_A00 #0 EBI_A06 #3	TIM2_CC0 #1 WTIM0_CDTI0 #2 WTIM2_CC0 #1 LETIM1_OUT0 #2 PCNT1_S0IN #5	CAN1_RX #5 US0_CLK #5 US2_RTS #2	CMU_CLK0 #5 PRS_CH12 #0 ACMP1_O #3
PA14	BUSBY BUSAX LCD_BEXT	EBI_REn #1 EBI_A02 #0 EBI_A08 #3	TIM2_CC2 #1 WTIM0_CDTI2 #2 WTIM2_CC2 #1 LETIM1_OUT1 #2	US1_TX #6 US2_RX #3 US3_RTS #2	PRS_CH14 #0 ACMP1_O #4
PB11	BUSAY BUSBX VDAC0_OUT0 / OPA0_OUT IDAC0_OUT	EBI_BL1 #2 EBI_A02 #1 EBI_A11 #3	TIM0_CDTI2 #4 TIM1_CC2 #3 WTIM2_CC2 #2 LETIM0_OUT0 #1 PCNT0_S1IN #7 PCNT1_S0IN #6	US0_CTS #5 US1_CLK #5 US2_CS #3 US5_CLK #0 U1_CTS #2 I2C1_SDA #1	CMU_CLK1 #5 CMU_CLKI0 #7 PRS_CH21 #2 ACMP0_O #3 GPIO_EM4WU7
PH1	BUSADC1Y BUSADC1X	EBI_DTEN #2		US0_RTS #6 LEU1_RX #5	
PH4	BUSADC1Y BUSADC1X	EBI_A16 #2	TIM6_CC2 #3 WTIM2_CC0 #6	US4_TX #4	
PH7	BUSADC1Y BUSADC1X	EBI_A19 #2	TIM6_CDTI2 #3 WTIM2_CC0 #7	US4_CS #4	
PH10	BUSACMP3Y BUSACMP3X	EBI_A22 #2	TIM6_CC2 #4 WTIM1_CC2 #6	US5_TX #3	

GPIO Name	Pin Alternate Functionality / Description				
	Analog	EBI	Timers	Communication	Other
PB13	BUSAY BUSBX HFXTAL_P		TIM6_CC0 #5 WTIM1_CC0 #0 PCNT2_S0IN #2	US0_CLK #4 US1_CTS #5 US5_CS #0 LEU0_TX #1	CMU_CLKI0 #3 PRS_CH7 #0
PB14	BUSBY BUSAX HFXTAL_N		TIM6_CC1 #5 WTIM1_CC1 #0 PCNT2_S1IN #2	US0_CS #4 US1_RTS #5 US5_CTS #0 LEU0_RX #1	PRS_CH6 #1
PD1	VDAC0_OUT1ALT / OPA1_OUTALT #4 BUSADC0Y BUSADC0X OPA3_OUT	EBI_A05 #1 EBI_A14 #3	TIM4_CDTI1 TIM0_CC0 #2 TIM6_CC0 #6 WTIM1_CC3 #0 PCNT2_S1IN #0	CAN0_TX #2 US1_RX #1	DBG_SWO #2
PD6	BUSADC0Y BUSADC0X ADC0_EXTP VDAC0_EXT ADC1_EXTP OPA1_P	EBI_A10 #1 EBI_A19 #3	TIM1_CC0 #4 TIM6_CC2 #7 WTIM0_CDTI2 #4 WTIM1_CC0 #2 LETIM0_OUT0 #0 PCNT0_S0IN #3	US0_RTS #5 US1_RX #2 US2_CTS #5 US3_CTS #2 U0_RTS #5 I2C0_SDA #1	CMU_CLK2 #2 LES_ALTEX0 PRS_CH5 #2 ACMP0_O #2 ETM_TD0 #0

Alternate	LOCATION		
Functionality	0 - 3	4 - 7	Description
ETH_MDIO	0: PB3 1: PD13 2: PC0 3: PA15		Ethernet Management Data I/O.
ETH_MIICOL	0: PB2 1: PG15 2: PB4		Ethernet MII Collision Detect.
ETH_MIICRS	0: PB1 1: PG14 2: PB3		Ethernet MII Carrier Sense.
ETH_MIIRXCLK	0: PA15 1: PG7 2: PD12		Ethernet MII Receive Clock.
ETH_MIIRXD0	0: PE12 1: PG11 2: PF9		Ethernet MII Receive Data Bit 0.
ETH_MIIRXD1	0: PE13 1: PG10 2: PD9		Ethernet MII Receive Data Bit 1.
ETH_MIIRXD2	0: PE14 1: PG9 2: PD10		Ethernet MII Receive Data Bit 2.
ETH_MIIRXD3	0: PE15 1: PG8 2: PD11		Ethernet MII Receive Data Bit 3.
ETH_MIIRXDV	0: PE11 1: PG12 2: PF8		Ethernet MII Receive Data Valid.
ETH_MIIRXER	0: PE10 1: PG13 2: PF7		Ethernet MII Receive Error.
ETH_MIITXCLK	0: PA0 1: PG0		Ethernet MII Transmit Clock.
ETH_MIITXD0	0: PA4 1: PG4		Ethernet MII Transmit Data Bit 0.
ETH_MIITXD1	0: PA3 1: PG3		Ethernet MII Transmit Data Bit 1.

Alternate	LOCATION		
Functionality	0 - 3	4 - 7	Description
LCD_SEG7	0: PE11		LCD segment line 7.
LCD_SEG8	0: PE12		LCD segment line 8.
LCD_SEG9	0: PE13		LCD segment line 9.
LCD_SEG10	0: PE14		LCD segment line 10.
LCD_SEG11	0: PE15		LCD segment line 11.
LCD_SEG12	0: PA15		LCD segment line 12.
LCD_SEG13	0: PA0		LCD segment line 13.
LCD_SEG14	0: PA1		LCD segment line 14.
LCD_SEG15	0: PA2		LCD segment line 15.
LCD_SEG16	0: PA3		LCD segment line 16.
LCD_SEG17	0: PA4		LCD segment line 17.
LCD_SEG18	0: PA5		LCD segment line 18.
LCD_SEG19	0: PA6		LCD segment line 19.

Alternate	LOCATION		
Functionality	0 - 3	4 - 7	Description
US3_RTS	0: PA5 1: PC1 2: PA14 3: PC15	4: PG5 5: PG11	USART3 Request To Send hardware flow control output.
US3_RX	0: PA1 1: PE7 2: PB7 3: PG7	4: PG1 5: PI13	USART3 Asynchronous Receive. USART3 Synchronous mode Master Input / Slave Output (MISO).
US3_TX	0: PA0 1: PE6 2: PB3 3: PG6	4: PG0 5: PI12	USART3 Asynchronous Transmit. Also used as receive input in half duplex communication. USART3 Synchronous mode Master Output / Slave Input (MOSI).
US4_CLK	0: PC4 1: PD11 2: PI2 3: PI8	4: PH6	USART4 clock input / output.
US4_CS	0: PC5 1: PD12 2: PI3 3: PI9	4: PH7	USART4 chip select input / output.
US4_CTS	0: PA7 1: PD13 2: PI4 3: PI10	4: PH8	USART4 Clear To Send hardware flow control input.
US4_RTS	0: PA8 1: PD14 2: PI5 3: PI11	4: PH9	USART4 Request To Send hardware flow control output.
US4_RX	0: PB8 1: PD10 2: PI1 3: PI7	4: PH5	USART4 Asynchronous Receive. USART4 Synchronous mode Master Input / Slave Output (MISO).
US4_TX	0: PB7 1: PD9 2: PI0 3: PI6	4: PH4	USART4 Asynchronous Transmit. Also used as receive input in half duplex communication. USART4 Synchronous mode Master Output / Slave Input (MOSI).
US5_CLK	0: PB11 1: PD13 2: PF13 3: PH12		USART5 clock input / output.
US5_CS	0: PB13 1: PD14 2: PF12 3: PH13		USART5 chip select input / output.
US5_CTS	0: PB14 1: PD15 2: PF11 3: PH14		USART5 Clear To Send hardware flow control input.
US5_RTS	0: PB12 1: PB15 2: PF10 3: PH15		USART5 Request To Send hardware flow control output.

Port	Bus	CH31	CH30	CH29	CH28	CH27	CH26	CH25	CH24	CH23	CH22	CH21	CH20	CH19	CH18	CH17	CH16	CH15	CH14	CH13	CH12	CH11	CH10	CH9	CH8	CH7	CH6	CH5	CH4	CH3	CH2	CH1	CH0
VDAC0_OUT1 / OPA1_OUT																																	
APORT1Y	BUSAY	PB15		PB13		PB11		PB9				PB5		PB3		PB1		PA15		PA13		PA11		PA9		PA7		PA5		PA3		PA1	
APORT2Y	BUSBY		PB14		PB12		PB10				PB6		PB4		PB2		PB0		PA14		PA12		PA10		PA8		PA6		PA4		PA2		PA0
APORT3Y	BUSCY	PF15		PF13		PF11		PF9		PF7		PF5		PF3		PF1		PE15		PE13		PE11		PE9		PE7		PE5				PE1	
APORT4Y	BUSDY		PF14		PF12		PF10		PF8		PF6		PF4		PF2		PF0		PE14		PE12		PE10		PE8		PE6		PE4				PE0

Table 7.1. BGA152 Package Dimensions

Dimension	Min	Typ	Max
A	0.78	0.84	0.90
A1	0.13	0.18	0.23
A3	0.16	0.20	0.24
A2		0.45 REF	
D		8.00 BSC	
e		0.50 BSC	
E		8.00 BSC	
D1		6.50 BSC	
E1		6.50 BSC	
b	0.20	0.25	0.30
aaa		0.10	
bbb		0.10	
ddd		0.08	
eee		0.15	
fff		0.05	

Note:
1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.
3. Recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

Table 10.2. TQFP100 PCB Land Pattern Dimensions

Dimension	Min	Nom	Max
C1		15.4	
C2		15.4	
E		0.50 BSC	
X		0.30	
Y		1.50	

Note:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. This Land Pattern Design is based on the IPC-7351 guidelines.
3. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 µm minimum, all the way around the pad.
4. A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
5. The stencil thickness should be 0.125 mm (5 mils).
6. The ratio of stencil aperture to land pad size should be 1:1 for all perimeter pads.
7. A No-Clean, Type-3 solder paste is recommended.
8. The recommended card reflow profile is per the JEDEC/IPC J-STD-020C specification for Small Body Components.

10.3 TQFP100 Package Marking

Figure 10.3. TQFP100 Package Marking

The package marking consists of:

- PPPPPPPPPP – The part number designation.
- TTTTTT – A trace or manufacturing code. The first letter is the device revision.
- YY – The last 2 digits of the assembly year.
- WW – The 2-digit workweek when the device was assembled.